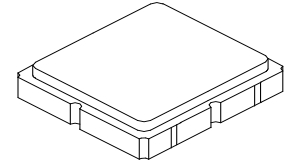


SF2678E

**169.4 MHz
SAW Filter**



SM3030-6

- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

Absolute Maximum Ratings

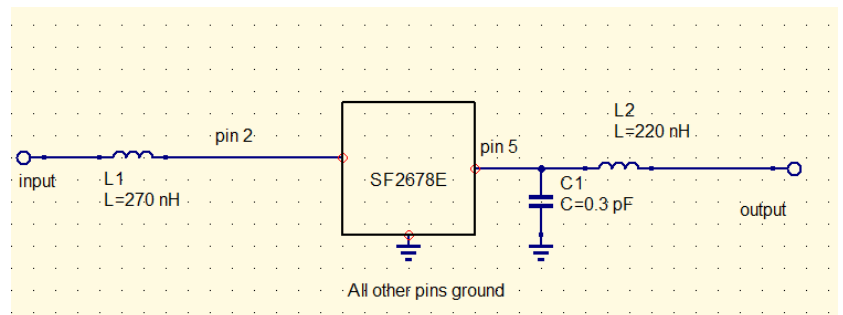
Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	6	V
Operating Temperature Range	-40 to +105	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 Cycles/10 seconds Maximum	265	°C

Electrical Characteristics

Characteristic	Notes	Min	Typ	Max	Units
Center Frequency			169.4375		MHz
1 dB Bandwidth			450		KHz
Insertion Loss 169.40625 MHz~169.46875MHz			2.7	3.3	dB
Attenuation Referenced to IL_{MAX} :					
165 MHz to 168.0688 MHz		12	15		dB
170.8063 MHz to 175 MHz		12	15		dB
10 MHz to 165 MHz		25	35		dB
175 MHz to 180 MHz		10	20		dB
180 MHz to 350 MHz		25	28		dB
350 MHz to 1000 MHz		40	45		dB
Source Impedance			50		ohm
Load Impedance			50		ohm

Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others



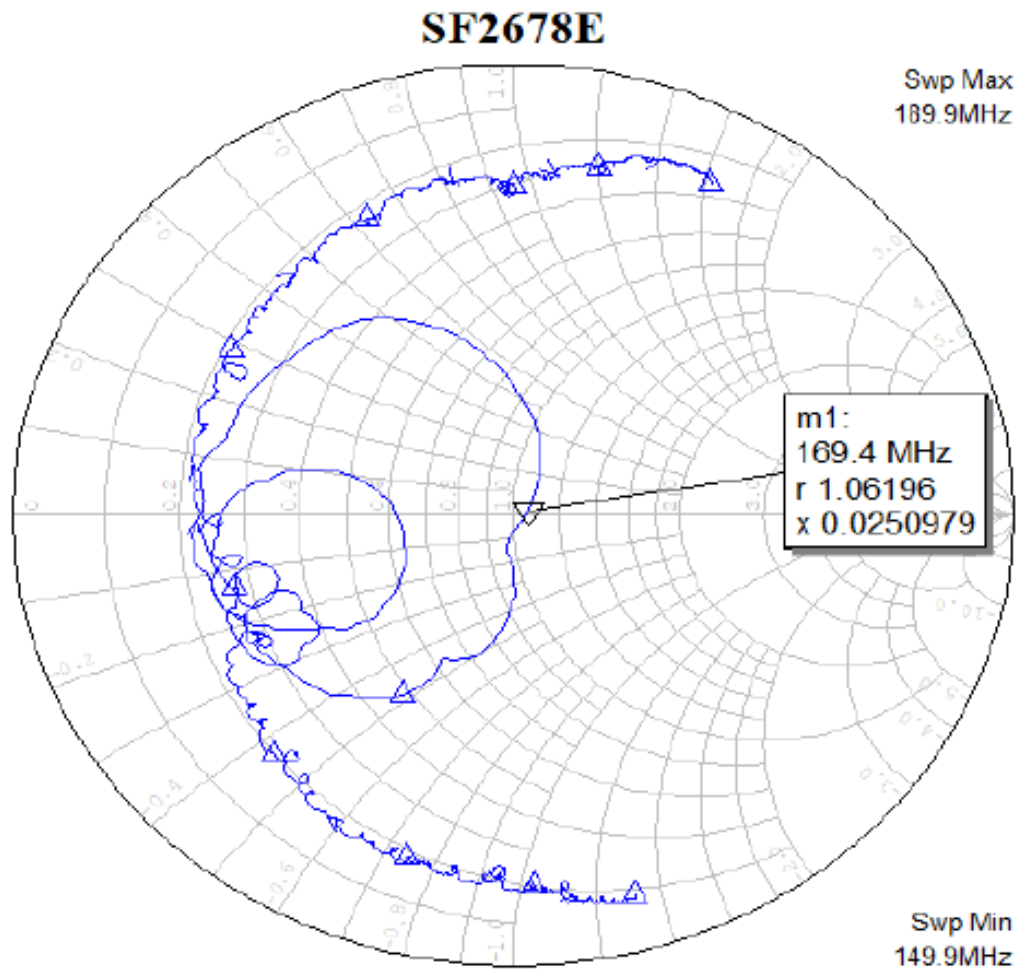


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

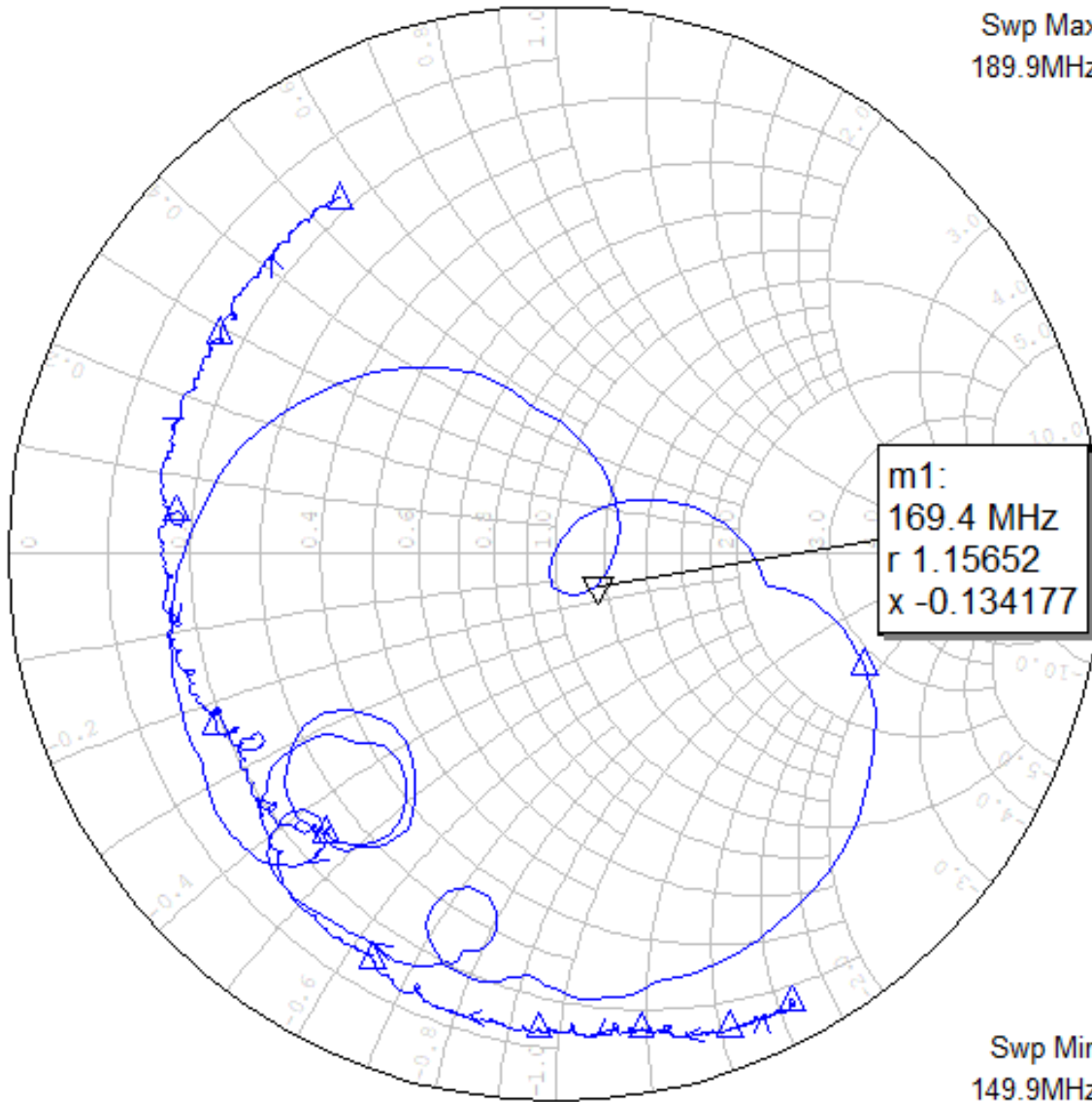
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Amplitude Response Plot

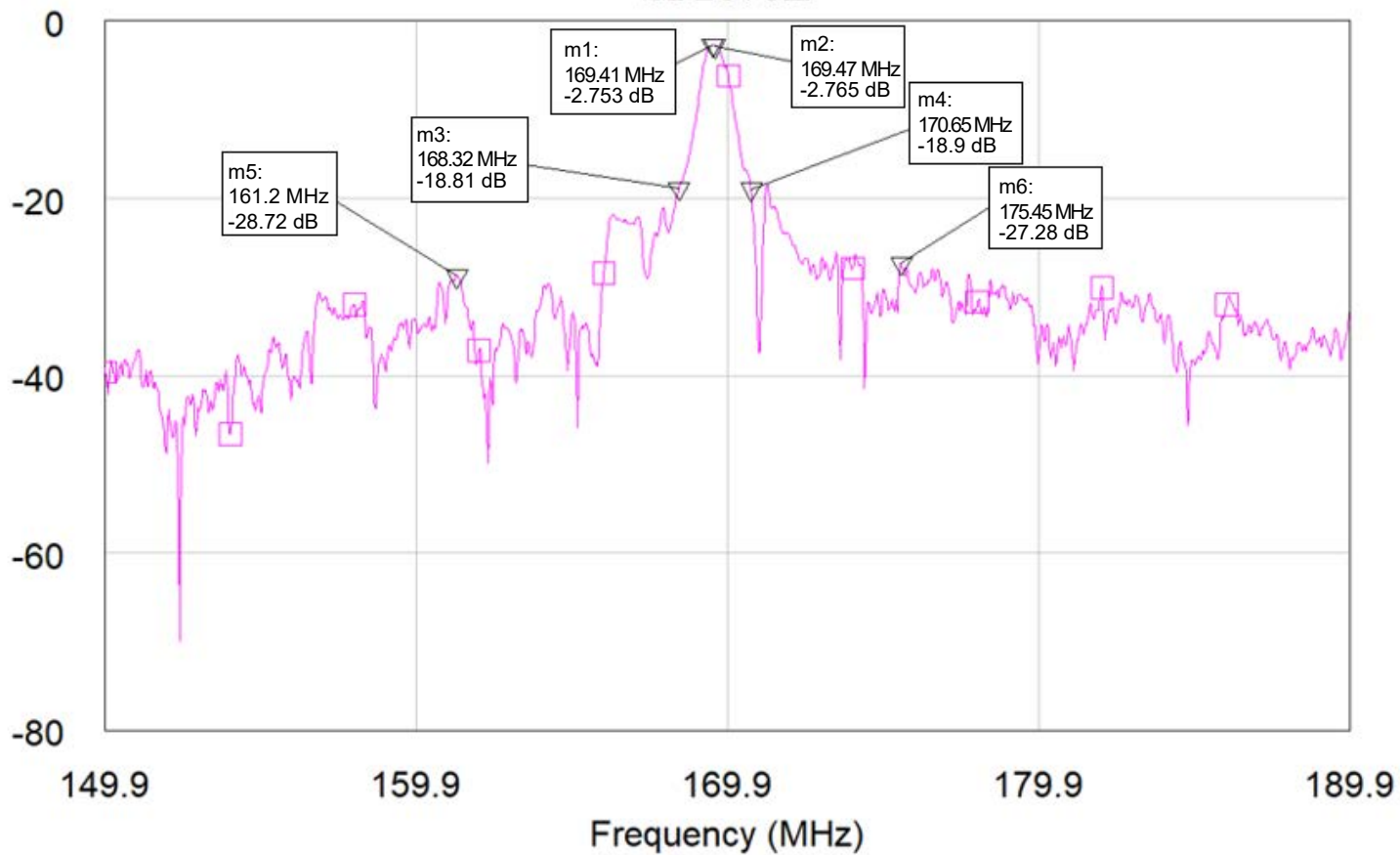


SF2678E

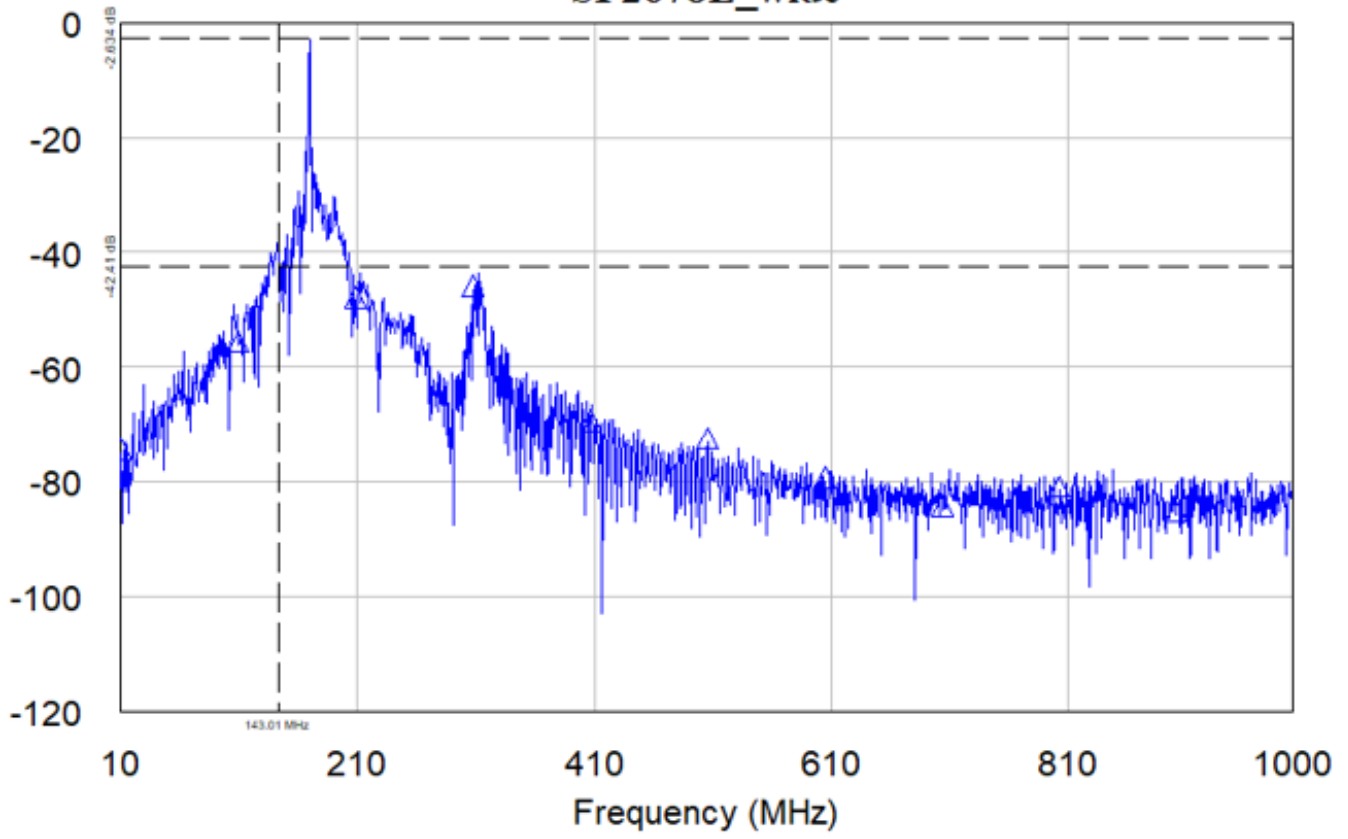
Swp Max
189.9MHz



SF2678E

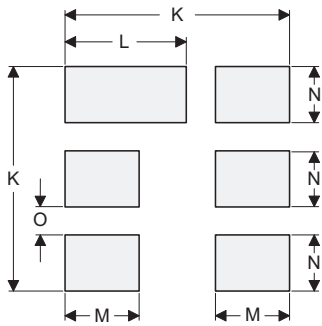
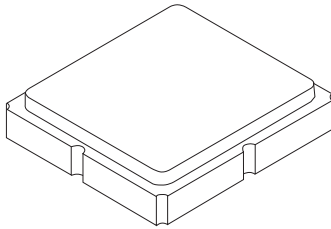


SF2678E_wide



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

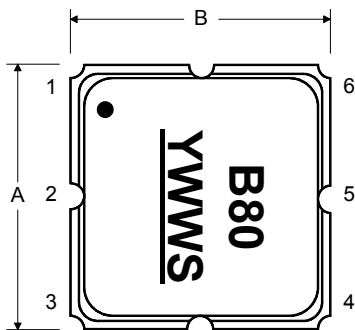
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.30	0.044	0.049	0.051
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

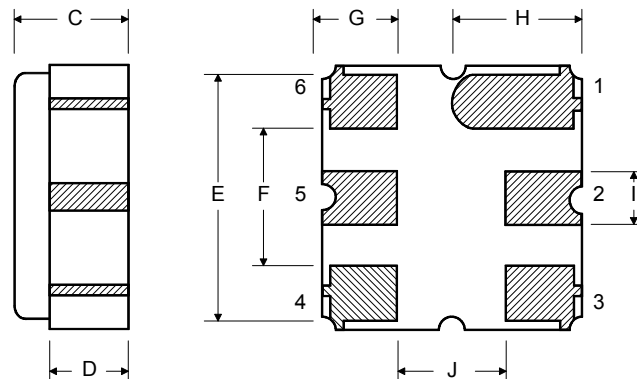
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

Top View

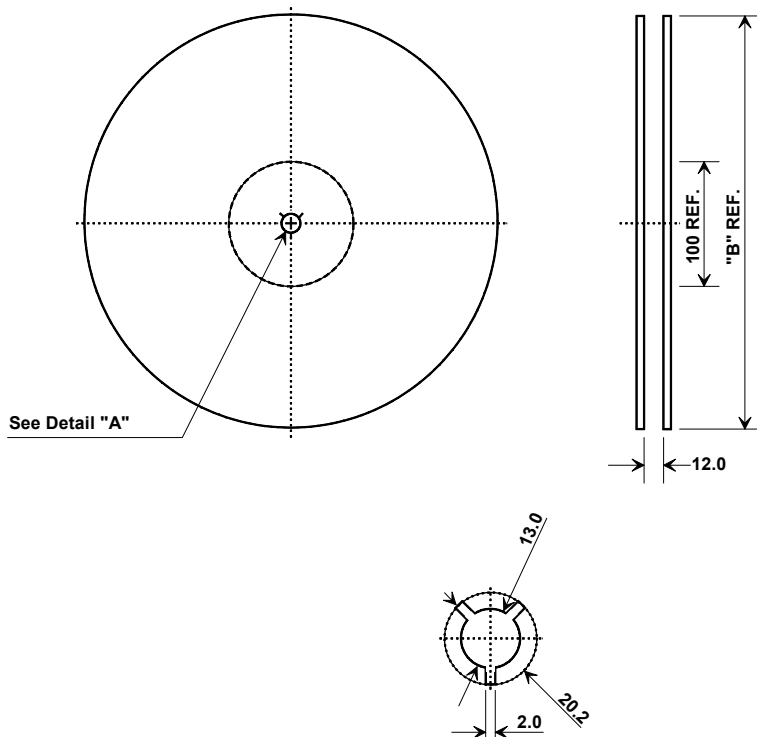


Bottom View



Tape and Reel Specifications

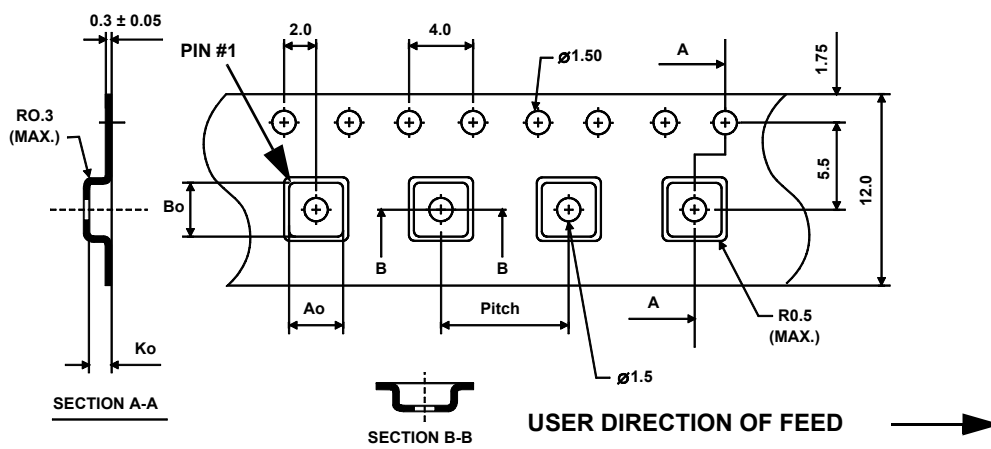
Tape and Reel Standard per ANSI/EIA-481



"B" Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

